# IC Package Substrate Report 2019

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## 1. Objective of this report

The purpose of this report is to provide relevant people in this market basic information to help them establish their business strategies by analyzing the trends of the IC Package Substrates for BGA and CSP.

## 2. Period of Survey

June 2019 - November 2019

## 3. Survey method

Direct interviews, questionnaires, newspapers, academic, technical journals and internet survey.

## 4. Remarks

- The market size is shown in global basis unless noted so.
- The data is calendar year basis.
- The classification between CSP and BGA in this report is ball pitch below 0.8mm is CSP and over 0.8mm is BGA.

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## Chapter 1 Summary

- Market Size Forecast of IC Package Substrates (2015-2028)
- Market Size Forecast of Flip Chip Substrates (2015-2028)
- Actual Sales of Major IC Substrate Manufacturers in 2018

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- Market Size of FCBGA Substrates by Applications/Layer Counts in 2018
  - Market Size of FCBGA Substrates by Applications in 2018
  - Market Size of FCBGA Substrates by Layer Counts in 2018
  - Market Size of FCBGA Substrates in Application Fields by Manufacturers/Layer Counts in 2018
  - Actual Sales of Major Manufacturers by Applications/Layer Counts in 2018
- Market Size Forecast of FCBGA Substrates by Applications (2015-2028)
- Market Size Forecast of FCBGA Substrates by Layer Counts (2015-2028)
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- Actual Sales of Major Manufacturers in 2018
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### **Chapter 4 Case Studies**

### <Japanese Manufacturers>

- 1. Ibiden Co., Ltd.
- 2. SHINKO ELECTRIC INDUSTRIES CO., LTD.
- 3. KYOCERA Corporation
- 4. Toppan Printing Co., LTD

## <Taiwanese Korean and Other Manufacturers>

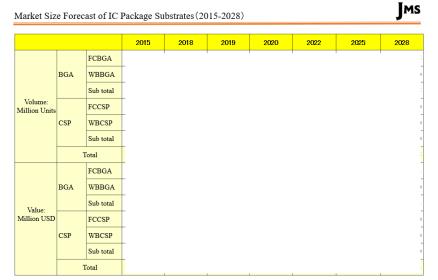
- 1. Unimicron Technology Corporation
- 2. Nan Ya Printed Circuit Board Corporation
- 3. Kinsus Interconnect Technology Corporation
- 4. Samsung Electro-Mechanics Company Limited
- 5. AT&S Austria Technologie & Systemtechnik AG

## <Survey items>

- 1. Company Profile
- 2. IC Package Substrate Business
  - 2-1. Manufacturing Sites
  - 2-2. Major Products
  - 2-3. Actual Sales of IC Package Substrates

## **Report Samples**

Jms



#### Market Size Forecast of FCCSP Substrates (2015-2028)



(Estimated by JMS)

#### (Estimated by JMS)

#### Market Size of FCBGA Substrates by Applications in 2018

	CY2018	MPU	GPU	Chipset	FPGA/Others	Total
	Ibiden					
	Unimicron					
	Shinko					
	Nan <u>Ya</u>					
	Kinsus					
Volume: Million Units	Kyocera					
vinnon Onits	SEMCO					
	AT&S					
	Toppan					
	Others					
	Total					
	Ibiden					
	Unimicron	_				
	Shinko					
	Nan <u>Ya</u>					
	Kinsus					
Value: Million USD	Kyocera					
	SEMCO					
	AT&S					
	Toppan					
	Others					
	Total					

#### Market Size of FCBGA Substrates by Layer Counts in 2018

Jms

CY2	018	1-N-	1	2-N-2	3-N-3	4-N-4	5-N-5	Others	Total
	Ibiden								
	Unimicron								]
	Shinko								]
	Nan <u>Ya</u>								]
	Kinsus								]
Volume: Million Units	Kyocera								
Willion Clints	SEMCO								
	AT&S								]
	Toppan								]
	Others								
	Total								]
	Ibiden								]
	Unimicron								]
	Shinko								]
	Nan Ya								
17-1	Kinsus								
Value: Million USD	Kyocera								]
Wintion CSD	SEMCO								
	AT&S								]
	Toppan								]
	Others								]
	Total								
(Estimated b	y JMS)								26

\*\* Others=6-N-6 or more, 2.5D Packaging

Jms

## **Report Samples**

## Jms

### AT & S Austria Technologie & Systemtechnik AG

https://ats.net/

1. Company Profile

Headquarters	Fabriksgasse 13, 8700 Leoben Osterreich, Austria						
Capital	141	Number of Employees		10,000 (including leased personnel)			
		2014	201	5	2016	2017	2018
Consolidated S	ales		20 93			• 6	

Unit: Million Euro Fiscal year-end: December Capital and Number of Employees: as of March 31, 2019

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#### 2-2. Manufacturing Sites of IC Package Substrates

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	Major Products	Technologies	Capacity (m/Y)
		٠F	
Shanghai Plant	HDI	•S	
Shanghai Flain		٠F	I.
		• 1	
	IC PKG, SLP	Fl	
		•E	
		٠E	
Change ing Diant		• 1	
Chongqing Plant		•s	1
		•£	
		•E	
		• Suosuano ante a C255	L

(Estimated by JMS)



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